



iNEMI

International Electronics Manufacturing Initiative

**IEEE/CPMT Participation
in Roadmap**



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

Rolf Aschenbrenner
European Kick-Off Meeting

The IEEE Components, Packaging and Manufacturing Technology (CPMT) Society is a international forum for scientists and engineers.

•Academia:

- **Create new knowledge**
- **Educate students**

•Industry:

- **Produce products using new knowledge & talent**
- **Create applied knowledge**

•Government:

- **Fund Basic infrastructure in science & engineering research and education**



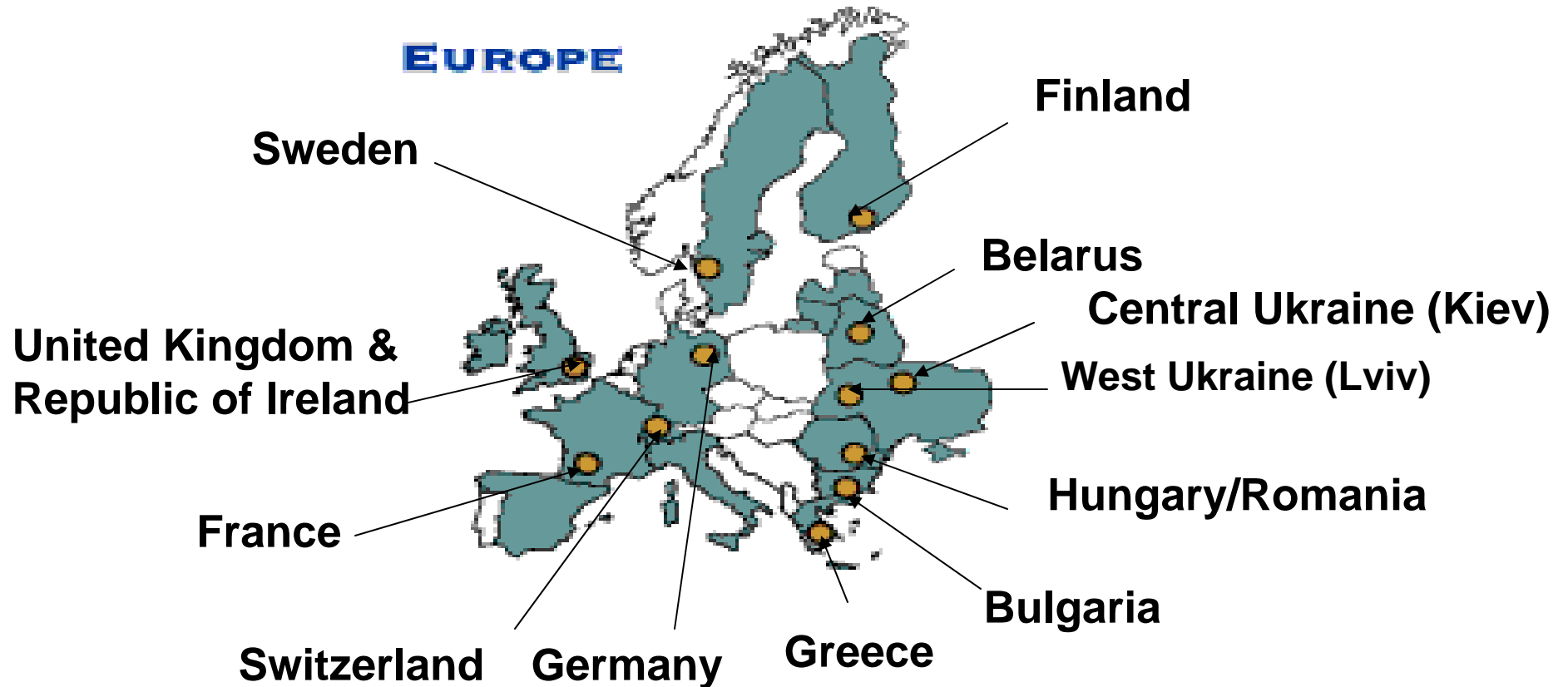
**IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY**

What is the Role of the CPMT Society?

- **Distribute knowledge - latest technology advancements**
 - *4 Transactions*, 30 conferences/workshops, Website
 - Chapter meetings, email, DL Lists
- **Develop professional skills: Education, Training, Tutorials**
- **Life-long learning**



IEEE CPMT Region 8



BoG Members Region 8



Rolf Aschenbrenner
Vice President Conferences
Fraunhofer IZM, Berlin, Germany



Eric Beyne

IMEC, Leuven, Belgium



Prof. Dr.-Ing. Klaus Jürgen Wolter

Technical University of Dresden , Germany

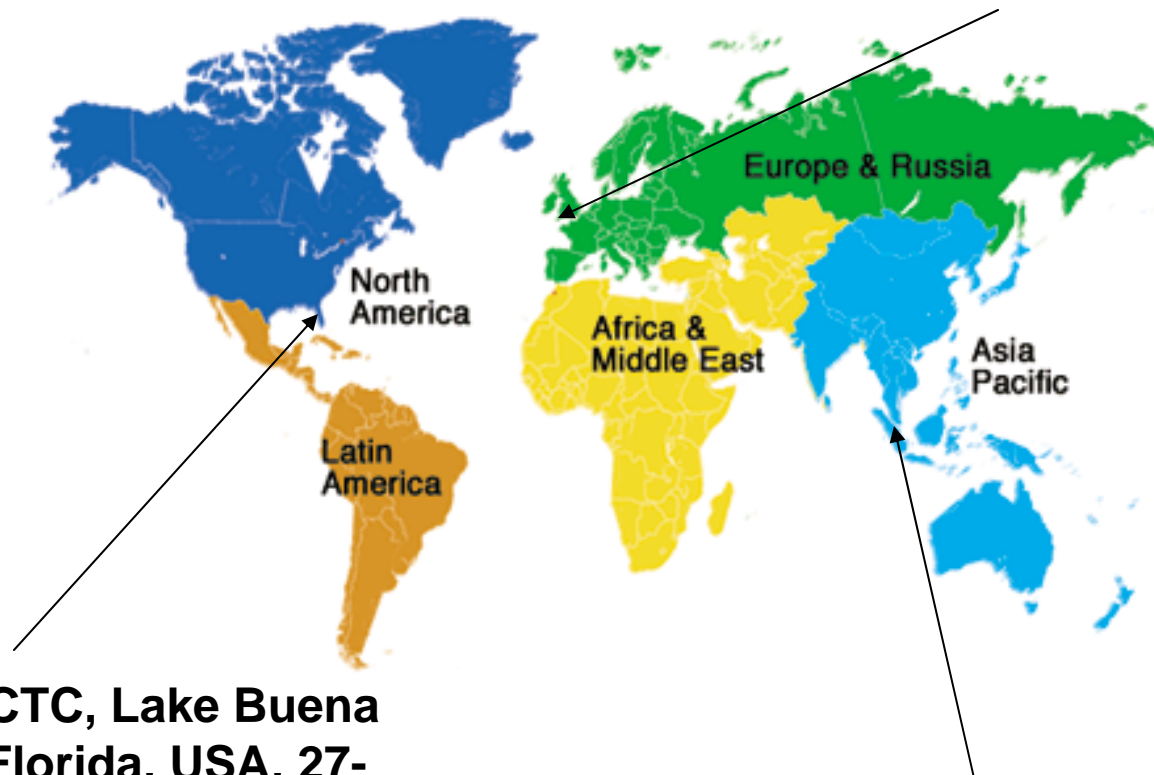


Dr. Tech. Petri Savolainen

Nokia Corporation, Helsinki, Finland

Three Flagship Conferences: ECTC, ESTC, EPTC

2nd ESTC, Greenwich, London, Great Britain,
1-4 September 2008



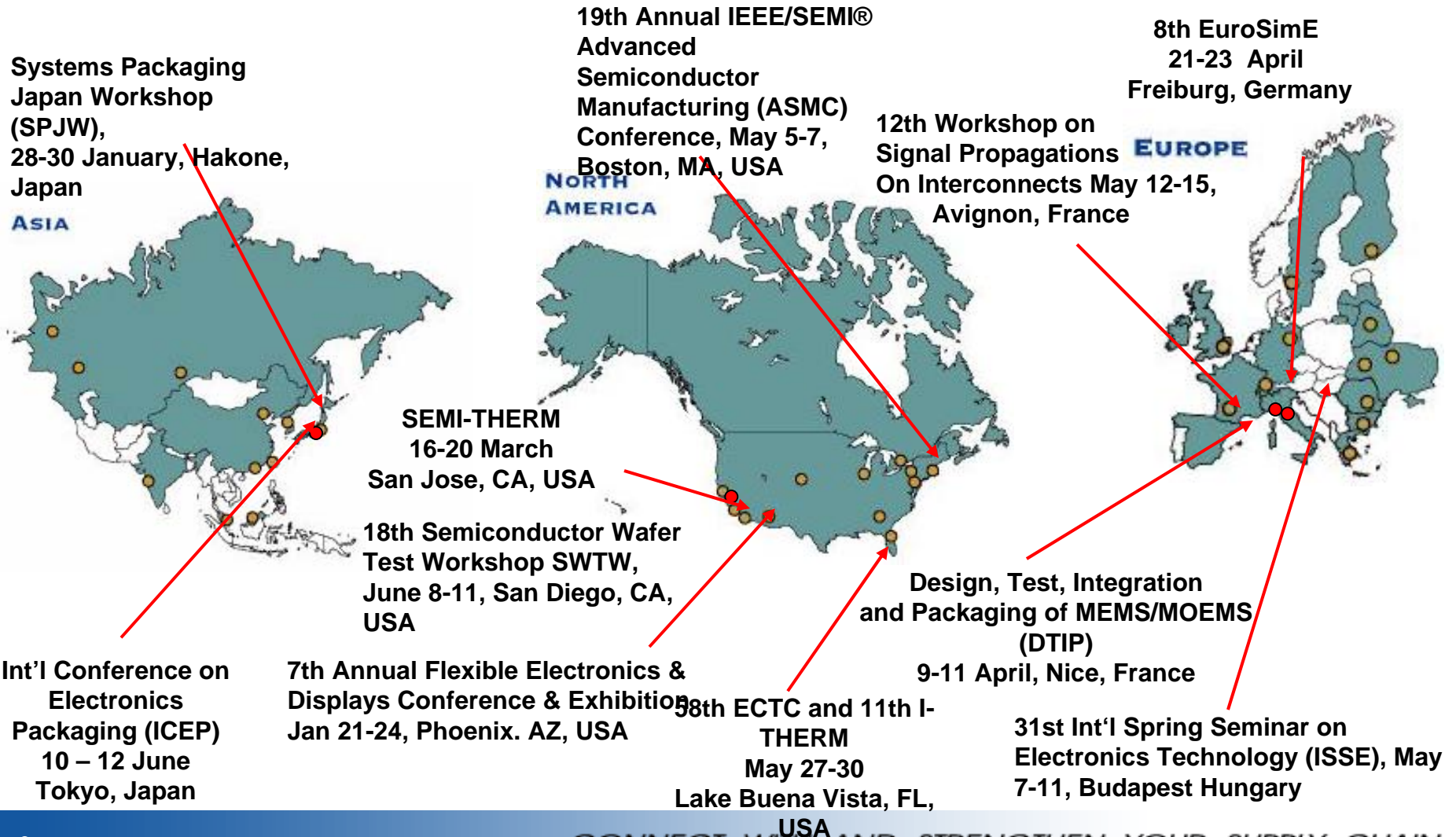
58th ECTC, Lake Buena
Vista, Florida, USA, 27-
30 May, 2008

9th EPTC, Singapore, 10-12 December,
2007

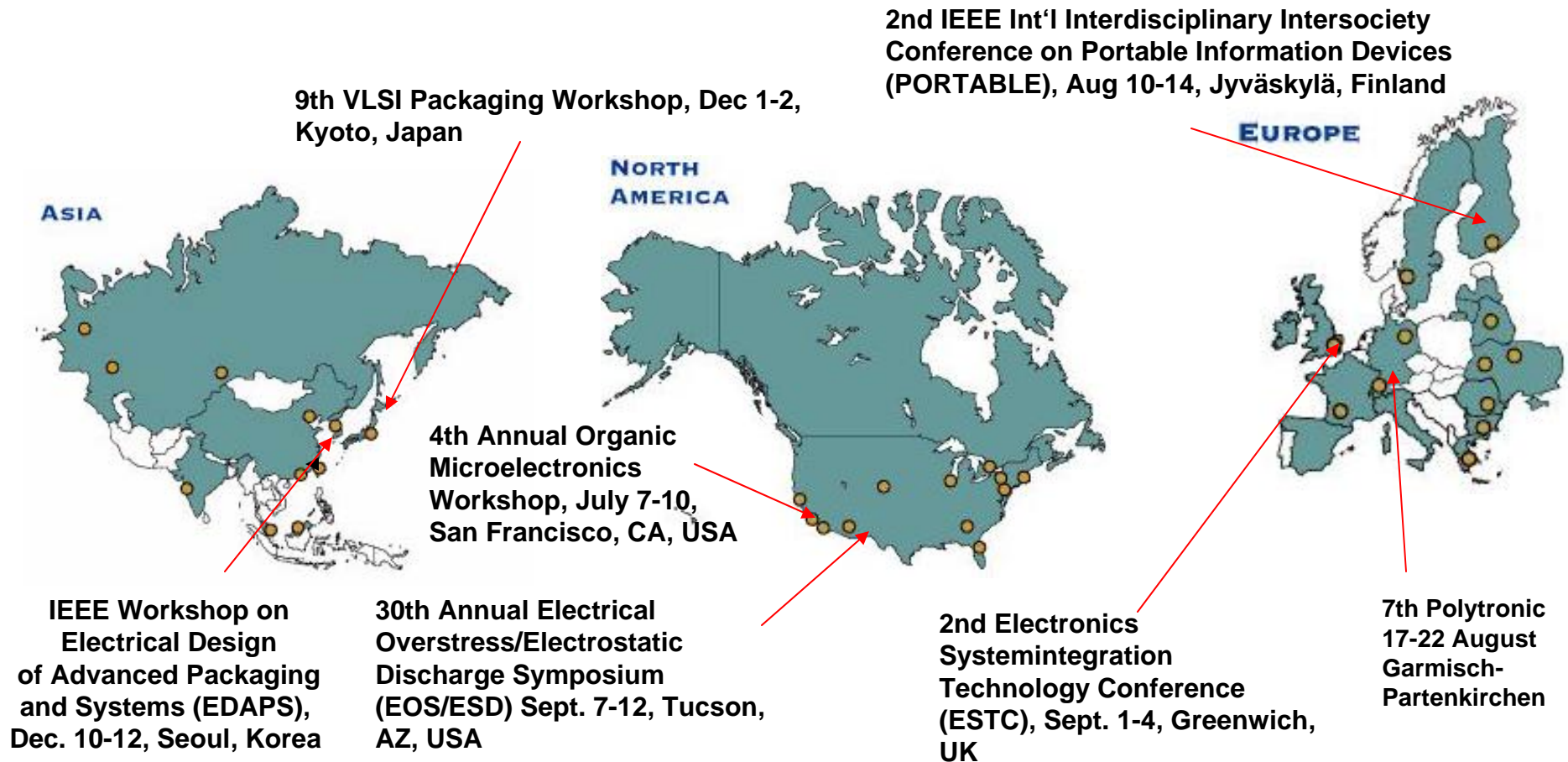


IEEE COMPONENTS, PACKAGING AND
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2008 Highlights Conferences (first half-year)



2008 Highlights Conferences (second half-year)



CPMT Focus In Technical Areas

TC-Nano Nano Packaging

Rao Tummala

TC-M Materials

Rajen Chanchani

TC-ASTR Accelerated Stress Testing and Reliability
Gibbel

Mark

TC-Opto Fiber Optics & Photonics

Sue Law

TC-Test Electrical Tests

Bruce Kim

TC-EDMS Electrical Design, Modeling and Simulation

M. Swaminathan

TC-Therm Thermal Management

Tony Mak

TC-Ed Education
Tummala

Rao

TC-ECCC Electrical Contacts, Connectors and Cables

Jerry Witter

TC-Assy IC and Packaging Assembly

M. Goetz

TC-HDSB High Density Substrates and Boards

Yoshitaka Fukuoka

TC-MEMS MEMS and Sensor Packaging

Erik Jung

TC-PEP Power Electronics Packaging

Douglas Hopkins

**TC-RF+W RF and Wireless
Gaw**

Craig A.

**TC-SP Systems Packaging
Klink**

Erich

TC-WLP Wafer Level Packaging

Michael Töpper

**TC-EM Electronics Manufacturing
Trybula**

Walter J.

TC-GEMP Green Electronics, Manufacturing and Packaging

Hansjörg

**9
Griese**

Benifits for CPMT

1. Insight into „hot topics“ in industry
2. Better ability to define workshops and conferences

www.cpmt.org

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